

REMARKS

Applicant has carefully reviewed and considered the Office Action mailed on September 11, 2003, and the references cited therewith.

Claims 1, 3, 4, 10-15, 20-22, and 26 are amended; as a result, claims 1-26 are now pending in this application.

Supplemental Information Disclosure Statement

Applicant respectfully requests that a copy of the 1449 Form, listing all references that were submitted with the Supplemental Information Disclosure Statement filed on December 30, 2002, marked as being considered and initialed by the Examiner, be returned with the next official communication.

§102 Rejection of the Claims

Claims 1-4 and 6-26 were rejected under 35 USC § 102(e) as being anticipated by Eichelberger et al. (U.S. 6,396,148).

Claims 1, 3, 4, 10-15, 20-22, and 26 are amended for clarity.

Independent claims 1, 10 and 20 recite a microelectronic die having a plurality of bond pads on an active surface of the microelectronic die. Claims 1, 10, and 20 also recite an interfacial metal layer having a conductive element that is conductively coupled to multiple bond pads. Claims 1, 10, and 20 are amended to clarify that the conductive element coupled to the multiple bond pads is a “single” (or separate) conductive element.

Eichelberger et al. disclose a die having a plurality of bond pads and conductive elements. However, Eichelberger et al. do not disclose a “single” conductive elements being coupled to “multiple” bond pads. None of the figures of Eichelberger et al. shows a “single” conductive element being coupled to “multiple” bond pads. For example, FIG. 1 and FIG. 2 of Eichelberger et al. show that element 108 is coupled to only a “single” bond pad of die 102. Notice that element 114 is also coupled to a “single” bond pad. FIG. 3G and FIG. 4F also show that element 109 is coupled to only a “single” bond pad. FIG. 6B and FIG. 7B also show that element 209 is coupled to only a “single” bond pad. Further, FIG. 6C and FIG. 7C show a solder

ball 234 being coupled to only a “single” bond pad. Thus, Eichelberger et al. do not disclose a “single” conductive element being coupled to “multiple” bond pads.

The reasons presented above demonstrate that claims 1, 10, and 20 are not anticipated by Eichelberger et al. Applicant respectfully requests that the rejection of claims 1, 10, and 20 be reconsidered and withdrawn and that claims 1, 10, and 20 be allowed.

Dependent claims 2-5, 7-9, 11-19, and 21-26 depend, directly or indirectly, on claims 1, 10, and 20, respectively, and are not anticipated by Eichelberger et al. for the reasons presented above, plus the elements in the dependent claims. Accordingly, Applicant requests that the rejection of claims claims 2-5, 7-9, 11-19, and 21-26 be reconsidered and withdrawn and that claims 2-5, 7-9, 11-19, and 21-26 be allowed.

§103 Rejection of the Claims

Claim 6 was rejected under 35 USC § 103(a) as being unpatentable over Eichelberger et al.

Dependent claim 6 depends on claim 1 and is patentable over Eichelberger et al. for the reasons presented above regarding claim 1, plus the elements in the dependent claim 6.

Accordingly, Applicant requests that the rejection of claim 6 be reconsidered and withdrawn and that claim 6 be allowed.

Serial Number: 09/845881

Dkt: 884.384US1 (INTEL)

Filing Date: April 30, 2001

Title: MICROELECTRONIC DEVICE HAVING SIGNAL DISTRIBUTION FUNCTIONALITY ON AN INTERFACIAL LAYER THEREOF

Assignee: Intel Corporation

Conclusion

Applicant respectfully submits that the claims are in condition for allowance and notification to that effect is earnestly requested. The Examiner is invited to telephone Applicant's representative (612) 373-6969 to facilitate prosecution of this application.

If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,

QUAT T. VU ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER
& KLUTH, P.A.

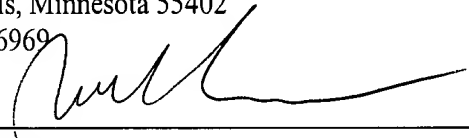
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Date 12-11-03

By 

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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop RCE, Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 11 day of December, 2003.

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Signature